54AC169 • 54ACT169 4-Stage Synchronous Bidirectional Counter

Check for Samples: 54AC169, 54ACT169

FEATURES

- **I_{CC} Reduced by 50%**
- **Synchronous Counting and Loading**
- **Built-In Lookahead Carry Capability**
- **Presettable for Programmable Operation**
- **Outputs Source/Sink 24 mA**
- **'ACT has TTL-Compatible Inputs**
- **Standard Microcircuit Drawing (SMD)**
  - **5962-91603**

DESCRIPTION

The 'AC/'ACT169 is fully synchronous 4-stage up/down counter. The 'AC/'ACT169 is a modulo-16 binary counter. It features a preset capability for programmable operation, carry lookahead for easy cascading and a U/$\overline{D}$ input to control the direction of counting. All state changes, whether in counting or parallel loading, are initiated by the LOW-to-HIGH transition of the Clock. ®

Logic Symbols

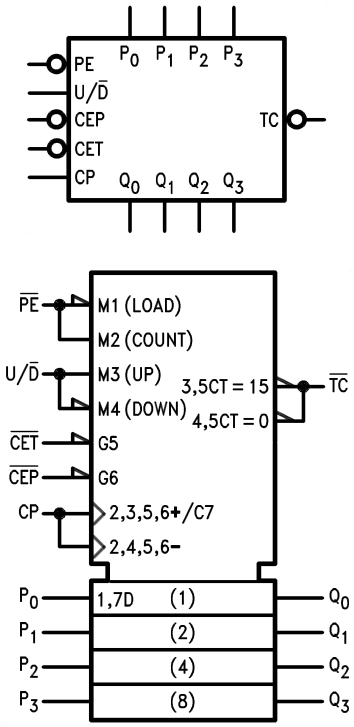


Figure 1. IEEE/IEC

Pin Names	Description
$\overline{CEP}$	Count Enable Parallel Input
$\overline{CET}$	Count Enable Trickle Input
CP	Clock Pulse Input
P_0–P_3	Parallel Data Inputs
$\overline{PE}$	Parallel Enable Input
U/$\overline{D}$	Up-Down Count Control Input
Q_0–Q_3	Flip-Flop Outputs
$\overline{TC}$	Terminal Count Output

Connection Diagrams

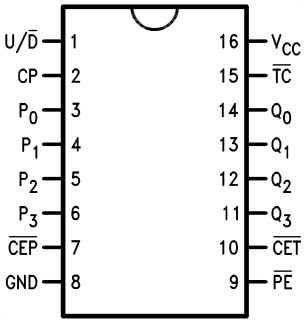


Figure 2. Pin Assignment for CDIP and CLGA See Package Numbers NFE and NAD

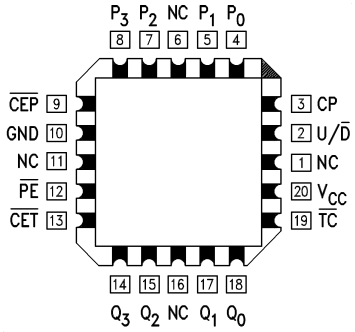
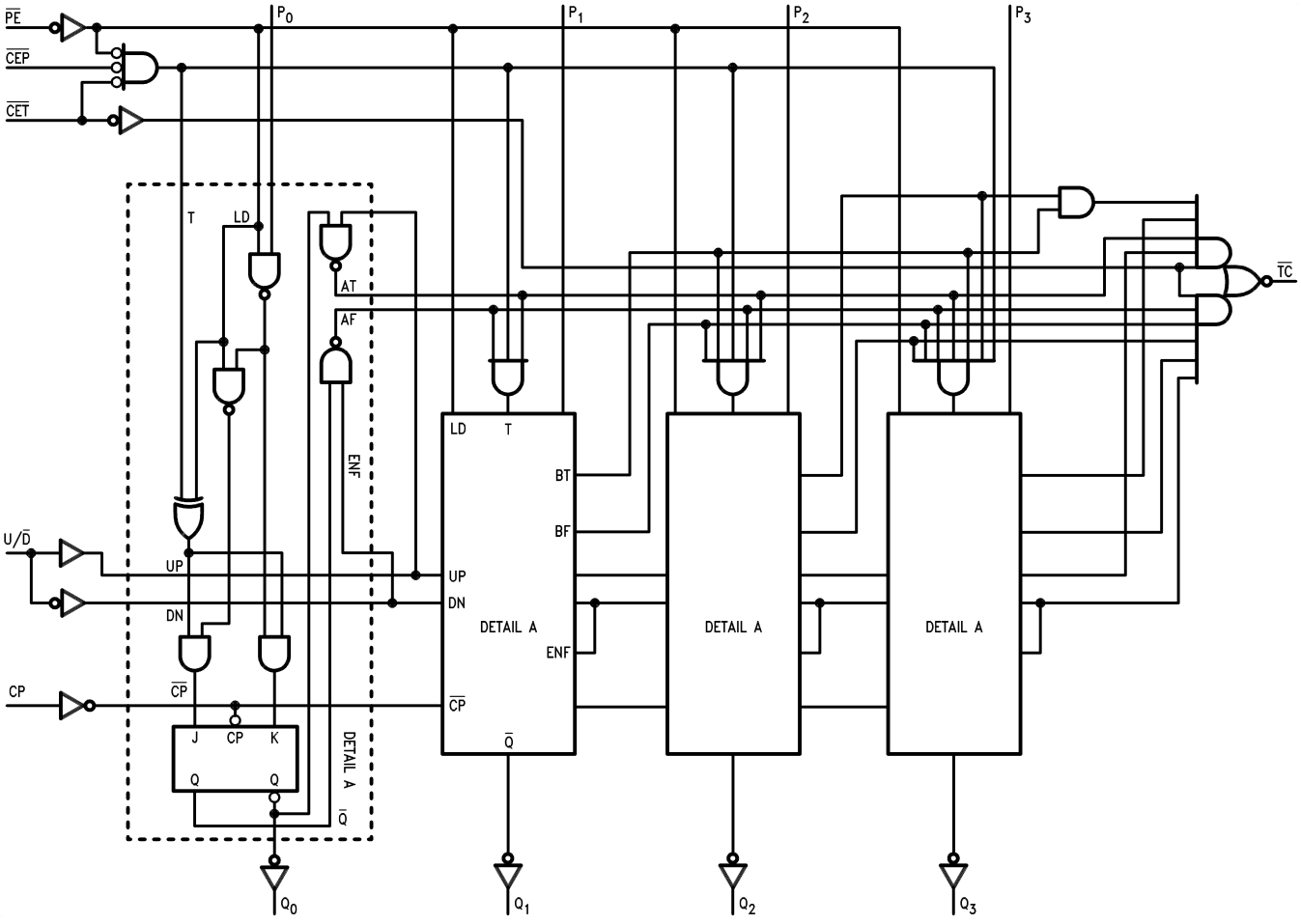


Figure 3. Pin Assignment for LCCC See Package Number NAJ

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

FUNCTIONAL DESCRIPTION

The 'AC/'ACT169 uses edge-triggered J-K-type flip-flops and have no constraints on changing the control or data input signals in either state of the Clock. The only requirement is that the various inputs attain the desired state at least a setup time before the rising edge of the clock and remain valid for the recommended hold time thereafter. The parallel load operation takes precedence over the other operations, as indicated in the Mode Select Table. When $\overline{PE}$ is LOW, the data on the P_0–P_3 inputs enters the flip-flops on the next rising edge of the Clock. In order for counting to occur, both $\overline{CEP}$ and $\overline{CET}$ must be LOW and $\overline{PE}$ must be HIGH; the U/$\overline{D}$ input then determines the direction of counting. The Terminal Count ($\overline{TC}$) output is normally HIGH and goes LOW, provided that $\overline{CET}$ is LOW, when a counter reaches zero in the Count Down mode or reaches 15 in the Count Up mode. The $\overline{TC}$ output state is not a function of the Count Enable Parallel ($\overline{CEP}$) input level. If an illegal state occurs, the 'AC169 will return to the legitimate sequence within two counts. Since the $\overline{TC}$ signal is derived by decoding the flip-flop states, there exists the possibility of decoding spikes on $\overline{TC}$. For this reason the use of $\overline{TC}$ as a clock signal is not recommended (see logic equations below).

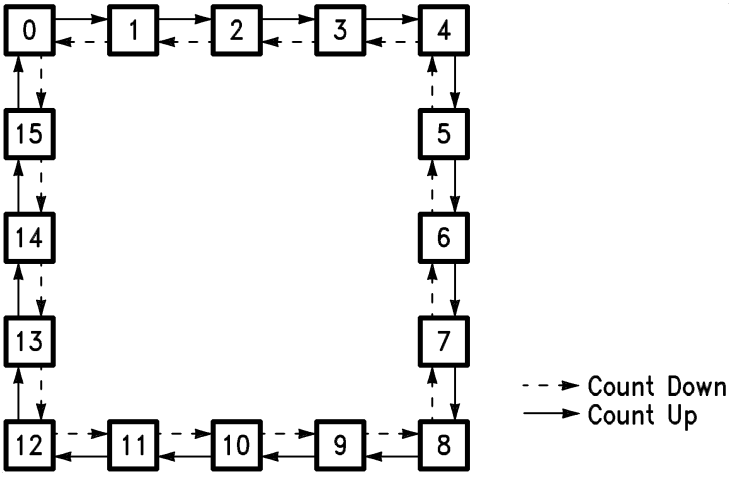
1. Count Enable = $\overline{CEP}$ •$\overline{CET}$ • $\overline{PE}$
2. Up: $\overline{TC}$ = Q_0•Q_1•$Q_2$$Q_3$•(Up)•$\overline{CET}$
3. Down: $\overline{TC}$ = $\overline{Q}_0$• $\overline{Q}_1$•$\overline{Q}_2$•$\overline{Q}_3$ •(Down)•$\overline{CET}$

Table 1. Mode Select Table(1)

$\overline{PE}$	$\overline{CEP}$	$\overline{CET}$	U/$\overline{D}$	Action on Rising Clock Edge
L	X	X	X	Load (P_n to Q_n)
H	L	L	H	Count Up (Increment)
H	L	L	L	Count Down (Decrement)
H	H	X	X	No Change (Hold)
H	X	H	X	No Change (Hold)

(1) H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

State Diagrams



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS (1)(2)

Supply Voltage (V_{CC})		−0.5V to +7.0V
DC Input Diode Current (I_{IK})	V_I = −0.5V	−20 mA
	V_I = V_{CC} + 0.5V	+20 mA
DC Input Voltage (V_I)		−0.5V to V_{CC} + 0.5V
DC Output Diode Current (I_{OK})	V_O = −0.5V	−20 mA
	V_O = V_{CC} + 0.5V	+20 mA
DC Output Voltage (V_O)		−0.5V to V_{CC} + 0.5V
DC Output Source or Sink Current (I_O)		±50 mA
DC V_{CC} or Ground Current per Output Pin (I_{CC} or I_{GND})		±50 mA
Storage Temperature (T_{STG})		−65°C to +150°C
Junction Temperature (T_J) CDIP		175°C

(1) Absolute Maximum Ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Texas Instruments does not recommend operation of FACT circuits outside databook specifications.

(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage (V_{CC})	'AC	2.0V to 6.0V
	'ACT	4.5V to 5.5V
Input Voltage (V_I)		0V to V_{CC}
Output Voltage (V_O)		0V to V_{CC}
Operating Temperature (T_A) 54AC/ACT		−55°C to +125°C
Minimum Input Edge Rate (ΔV/Δt)	'AC Devices	
	V_{IN} from 30% to 70% of V_{CC}	
	V_{CC} @ 3.3V, 4.5V, 5.5V	125 mV/ns
Minimum Input Edge Rate (ΔV/Δt)	'ACT Devices	
	V_{IN} from 0.8V to 2.0V	
	V_{CC} @ 4.5V, 5.5V	125 mV/ns

DC CHARACTERISTICS FOR 'AC FAMILY DEVICES

Symbol	Parameter	V_{CC} (V)	54AC T_A = −55°C to +125°C Specifiied Limits	Units	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0	2.1	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
		4.5	3.15		
		5.5	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	0.9	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
		4.5	1.35		
		5.5	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.9	V	I_{OUT} = −50 µA
		4.5	4.4		
		5.5	5.4		
					See(1) V_{IN} = V_{IL} or V_{IH}
		3.0	2.4		I_{OH} = −12 mA
		4.5	3.7	V	I_{OH} = −24 mA
		5.5	4.7		I_{OH} = −24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.1	V	I_{OUT} = 50 µA
		4.5	0.1		
		5.5	0.1		
					See(1) V_{IN} = V_{IL} or V_{IH}
		3.0	0.50		I_{OL} = 12 mA
		4.5	0.50	V	I_{OL} = 24 mA
		5.5	0.50		I_{OL} = 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	±1.0	µA	V_I = V_{CC}, GND
I_{OLD}	Minimum Dynamic Output Current(2)	5.5	50	mA	V_{OLD} = 1.65V Max
I_{OHD}		5.5	−50	mA	V_{OHD} = 3.85V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	80.0	µA	V_{IN} = V_{CC} or GND

(1) All outputs loaded; thresholds on input associated with output under test.
(2) Maximum test duration 2.0 ms, one output loaded at a time.

DC CHARACTERISTICS FOR 'ACT FAMILY DEVICES

Symbol	Parameter	V_{CC} (V)	54ACT T_A = −55°C to +125°C Specified Limits	Units	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	2.0 2.0	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	0.8 0.8	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.4 5.4	V	I_{OUT} = −50 µA
		 4.5 5.5	 3.70 4.70	 V	See(1) V_{IN} = V_{IL} or V_{IH} I_{OH} = −24 mA I_{OH} = −24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.1 0.1	V	I_{OUT} = 50 µA
		 4.5 5.5	 0.50 0.50	 V	See(1) V_{IN} = V_{IL} or V_{IH} I_{OL} = 24 mA I_{OL} = 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	±1.0	µA	V_I = V_{CC}, GND
I_{CCT}	Maximum I_{CC}/Input	5.5	1.6	mA	V_I = V_{CC} − 2.1V
I_{OLD}	Minimum Dynamic Output Current(2)	5.5	50	mA	V_{OLD} = 1.65V Max
I_{OHD}		5.5	−50	mA	V_{OHD} = 3.85V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	80.0	µA	V_{IN} = V_{CC} or GND

(1) All outputs loaded; thresholds on input associated with output under test.
(2) Maximum test duration 2.0 ms, one output loaded at a time.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)[1]	54AC T_A = −55°C to +125°C C_L = 50 pF		Units	Fig. No.
			Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	55 75		MHz	
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ HIGH or LOW)	3.3 5.0	1.0 1.5	15.0 12.0	ns	
t_{PHL}	Propagation Delay CP to Q_n ($\overline{PE}$ HIGH or LOW)	3.3 5.0	1.0 1.5	16.5 13.0	ns	
t_{PLH}	Propagation Delay CP to $\overline{TC}$	3.3 5.0	3.0 3.0	22.0 16.0	ns	
t_{PHL}	Propagation Delay CP to $\overline{TC}$	3.3 5.0	3.0 3.0	22.0 16.0	ns	
t_{PLH}	Propagation Delay $\overline{CET}$ to $\overline{TC}$	3.3 5.0	1.0 1.5	18.5 13.0	ns	
t_{PHL}	Propagation Delay $\overline{CET}$ to $\overline{TC}$	3.3 5.0	1.0 1.5	16.0 11.0	ns	
t_{PLH}	Propagation Delay U/$\overline{D}$ to $\overline{TC}$	3.3 5.0	1.0 1.5	18.5 13.0	ns	
t_{PHL}	Propagation Delay U/$\overline{D}$ to $\overline{TC}$	3.3 5.0	1.0 1.5	16.5 12.0	ns	

(1) Voltage Range 3.3 is 3.3V ±0.3V
Voltage Range 5.0 is 5.0V ±0.5V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC} (V)[1]	54AC T_A = −55°C to +125°C C_L = 50 pF	Units	Fig. No.
			Specified Minimum		
t_s	Setup Time, HIGH or LOW P_n to CP	3.3 5.0	7.0 4.5	ns	
t_h	Hold Time, HIGH or LOW P_n to CP	3.3 5.0	2.0 2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{CEP}$ to CP	3.3 5.0	13.5 9.0	ns	
t_h	Hold Time, HIGH or LOW $\overline{CEP}$ to CP	3.3 5.0	0.5 2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{CET}$ to CP	3.3 5.0	13.5 9.0	ns	

(1) Voltage Range 3.3 is 3.3V ±0.3V
Voltage Range 5.0 is 5.0V ±0.5V.

AC OPERATING REQUIREMENTS (continued)

Symbol	Parameter	V_{CC} (V)[1]	54AC T_A = −55°C to +125°C C_L = 50 pF Specified Minimum	Units	Fig. No.
t_h	Hold Time, HIGH or LOW $\overline{CET}$ to CP	3.3 5.0	0.5 2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	8.5 6.5	ns	
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	0.5 2.0	ns	
t_s	Setup Time, HIGH or LOW U/$\overline{D}$ to CP	3.3 5.0	13.0 9.0	ns	
t_h	Hold Time, HIGH or LOW U/$\overline{D}$ to $\overline{CP}$	3.3 5.0	0.5 2.0	ns	
t_w	CP Pulse Width, HIGH or LOW	3.3 5.0	5.0 5.0	ns	

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)[1]	54ACT T_A = −55°C to +125°C C_L = 50 pF		Units	Fig. No.
			Min	Max		
f_{max}	Maximum Clock Frequency	5.0	75		MHz	
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ HIGH or LOW)	5.0	1.5	12.5	ns	
t_{PHL}	Propagation Delay CP to Q_n ($\overline{PE}$ HIGH or LOW)	5.0	1.5	12.5	ns	
t_{PLH}	Propagation Delay CP to $\overline{TC}$	5.0	1.5	16.5	ns	
t_{PHL}	Propagation Delay CP to $\overline{TC}$	5.0	1.5	16.5	ns	
t_{PLH}	Propagation Delay $\overline{CET}$ to $\overline{TC}$	5.0	1.5	13.5	ns	
t_{PHL}	Propagation Delay $\overline{CET}$ to $\overline{TC}$	5.0	1.5	13.5	ns	
t_{PLH}	Propagation Delay U/$\overline{D}$ to $\overline{TC}$	5.0	1.5	14.5	ns	
t_{PHL}	Propagation Delay U/$\overline{D}$ to $\overline{TC}$	5.0	1.5	14.5	ns	

(1) Voltage Range 5.0 is 5.0V ±0.5V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC} (V)[1]	54ACT T_A = −55°C to +125°C C_L = 50 pF Specified Minimum	Units	Fig. No.
t_s	Setup Time, HIGH or LOW P_n to CP	5.0	4.5	ns	
t_h	Hold Time, HIGH or LOW P_n to CP	5.0	2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{CEP}$ to CP	5.0	9.0	ns	
t_h	Hold Time, HIGH or LOW $\overline{CEP}$ to CP	5.0	2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{CET}$ to CP	5.0	9.0	ns	
t_h	Hold Time, HIGH or LOW $\overline{CET}$ to CP	5.0	2.5	ns	
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	5.0	6.5	ns	
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	5.0	2.0	ns	
t_s	Setup Time, HIGH or LOW U/$\overline{D}$ to CP	5.0	9.0	ns	
t_h	Hold Time, HIGH or LOW U/$\overline{D}$ to $\overline{CP}$	5.0	2.0	ns	
t_w	CP Pulse Width, HIGH or LOW	5.0	5.0	ns	

(1) Voltage Range 5.0 is 5.0V ±0.5V.

CAPACITANCE

Symbol	Parameter	Typ	Units	Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = Open
C_{PD}	Power Dissipation Capacitance	60.0	pF	V_{CC} = 5.0V

REVISION HISTORY

Changes from Revision A (April 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format	9

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